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Kim et al.

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(54) **MOLD FOR PACKAGING SEMICONDUCTOR LIGHT EMITTING DEVICE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **26-99**

(52) **U.S. Cl.**
USPC **D26/120**

(58) **Field of Classification Search**
USPC D26/1, 24, 120, 138; D13/180
CPC H01J 5/48; H01J 5/50; H01J 19/54
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a mold for packaging semiconductor light emitting device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a mold for packaging semiconductor light emitting device, showing our new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a left side view thereof;

FIG. 5 is a right side view thereof;

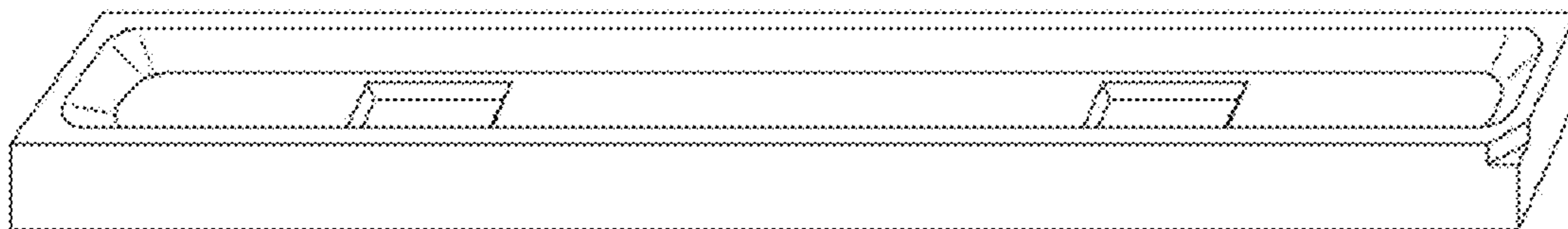
FIG. 6 is a top view thereof;

FIG. 7 is a bottom view thereof;

FIG. 8 is a sectional view thereof, taken generally along the line A-A' in FIG. 6; and,

FIG. 9 is a sectional view thereof, taken generally along the line B-B' in FIG. 6.

1 Claim, 3 Drawing Sheets



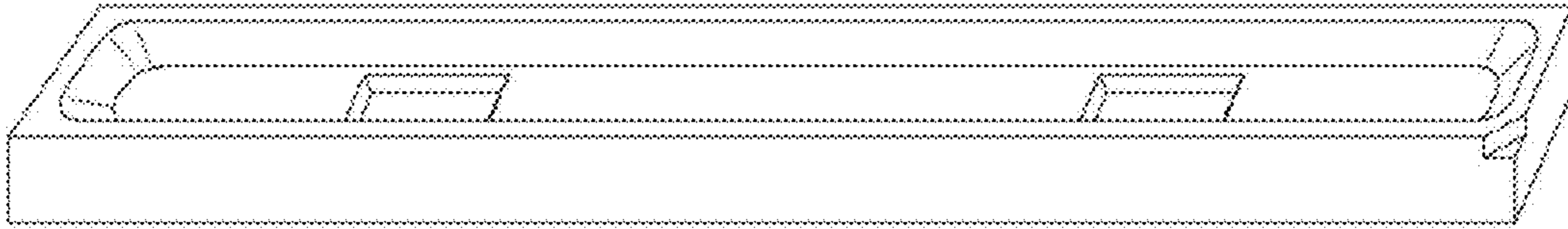


FIG. 1



FIG. 2



FIG. 3



FIG. 4



FIG. 5

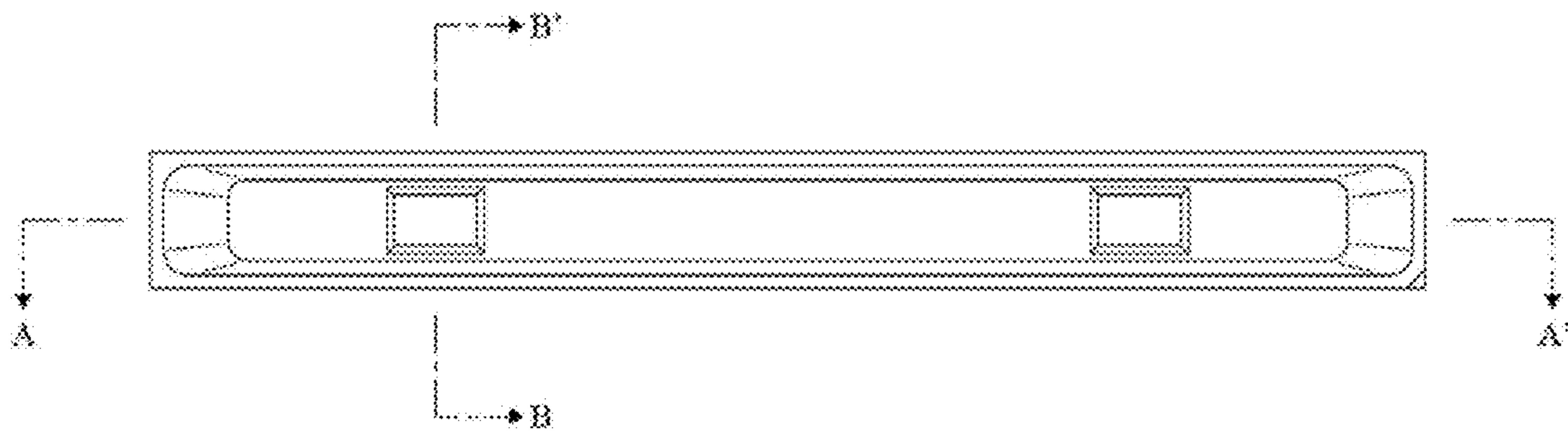


FIG. 6



FIG. 7

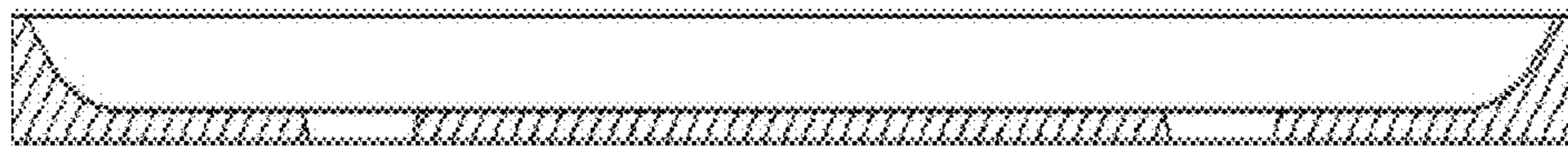


FIG. 8

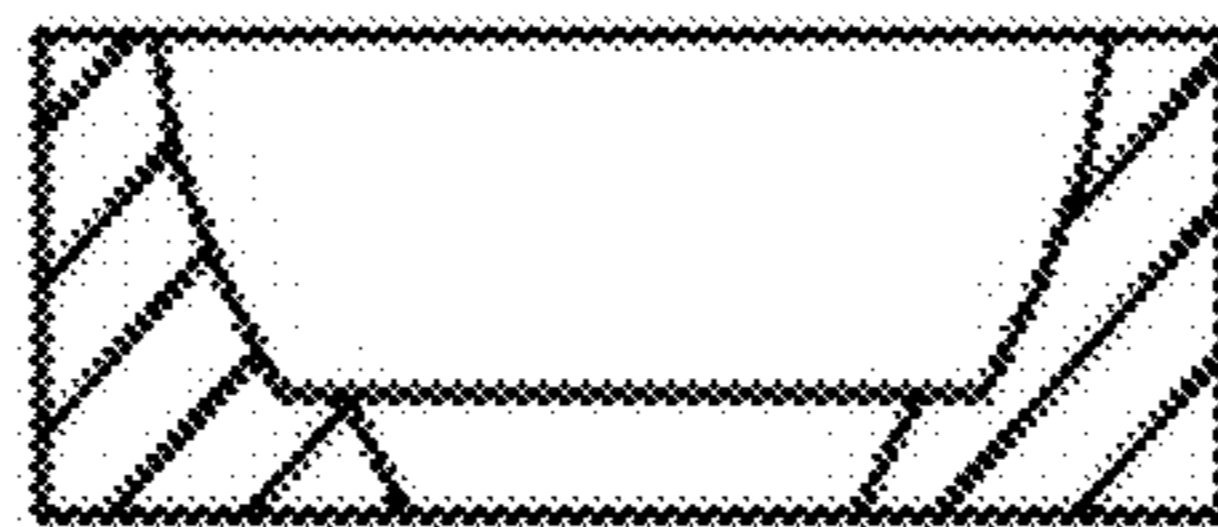


FIG. 9